

ASSIGNMENT

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WHEREAS, I/We

Dong-won KIM of 172-1, Namgajwa 2-dong, Sodamun-gu, Seoul, Republic of Korea

(hereinafter called ASSIGNOR) have invented certain new and useful improvements for a **METHOD OF ANALYZING A WAFER IN A SEMICONDUCTOR DEVICE FABRICATION PROCESS** for which an application for Letters Patent of the United States is filed herewith, claiming priority to Korean Patent Application No. 96-26767, filed July 2, 1996;

AND WHERE AS, SAMSUNG ELECTRONICS CO, LTD., of the Republic of Korea, a Korean corporation having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea (hereinafter called ASSIGNEE), desires to acquire the entire right, title and interest in and to said invention, said application and in, to and under any and all United States and foreign patents to be obtained therefore;

NOW THEREFORE, for good and valuable consideration paid to me/us by the said ASSIGNEE, receipt of which is hereby acknowledged, I/we do hereby sell, assign and transfer to ASSIGNEE, its successors and assigns, the entire right, title and interest in and to the application and the invention disclosed therein for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I/we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to ASSIGNEE, its successors and assigns; and I/we hereby agree that ASSIGNEE may apply for foreign patents on said invention and I/we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by ASSIGNEE.



Dong-won KIMon Date 03/24, 1997